

Appl No. 10/803,192  
Amdt dated August 8, 2006  
Reply to Office Action of May 17, 2006

Atty. Ref. 81754.0111  
Customer No. 26021

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

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1-3. (Canceled)

4. (Currently amended) A semiconductor device comprising:

a semiconductor chip having an integrated circuit and electrical interconnections electrically connected to the integrated circuit, the semiconductor chip including bonding pads formed on a surface of the semiconductor chip, each of the bonding pads being part of a corresponding electrical interconnection;

a first resin layer disposed on the semiconductor chip and having ridged edges;

wirings, each being disposed over and electrically connected to a corresponding bonding pad and extending integrally over the first resin layer and over a corresponding ridged edge of the first resin layer and being electrically connected to the corresponding bonding pad; and

external connection terminals, each being disposed on a corresponding wiring and being electrically connected to the corresponding wiring, and a part of each external connection terminal being disposed above and in vertical alignment with the corresponding ridged edge that the corresponding wiring extends over.

5-6. (Canceled)

7. (Original) A circuit board on which the semiconductor device according to claim 4 is mounted.

8. (Original) An electronic apparatus including the semiconductor device according to claim 4.

9-13. (Canceled)

14-15. (Canceled)

16. (Currently amended) A circuit board on which the semiconductor device according to claim 6 4 is mounted.

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17. (Canceled)

18. (Currently amended) An electronic apparatus including the  
semiconductor device according to claim 6 4.

19-20. (Canceled)